ELPAQ ELPAQ **EMS256K8B**

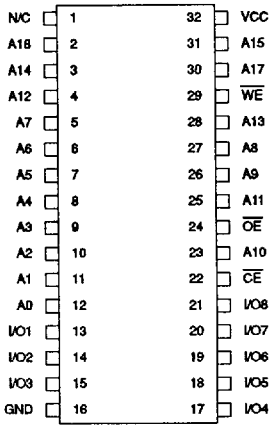
A division of ELMO *Semiconductor Corp.* ***35 - 55ns***

2Mb CMOS STATIC SRAM

FEATURES

- **High density SRAM module**
- **Organized as 262,144 x 8**
- **Access time 35 - 55ns**
- **Low power consumption**
  Standby: 100µW(typ.)
  Operating: 325mW(typ.)
- **Power supply voltage 5V±10%**
- **TTL compatible inputs and outputs**
- **Fully static operation**
- **32 pin DIP package**
- **JEDEC standard pinout**
- **MIL or commercial temperature range**

Pin Configuration



Pin Description

A0 - A17	Address Inputs
I/O1 - I/O8	Data Inputs/Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
VCC	Power Supply
GND	Ground

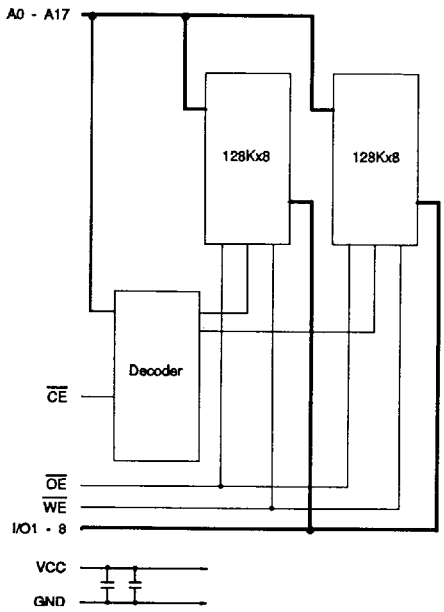
GENERAL DESCRIPTION

The ELPAQ EMS256Kx8B is a high performance 2Mb CMOS SRAM module organized as 262,144 bytes of 8 bits each, using two 1Mb SRAMs and a decoder. The EMS256Kx8B is packaged in a 32 lead 600 mil wide ceramic or plastic DIP package. The module is offered in a variety of temperature and speed combinations.

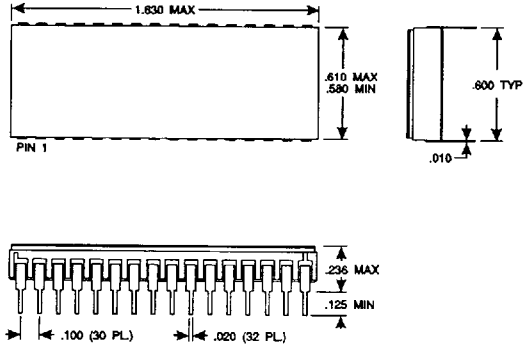
All inputs and outputs are TTL compatible and the module operates from a single 5V power supply. The EMS256Kx8B is a fully asynchronous SRAM and requires no clocks for operation. The module is also available in Low Power and Low Power with Data Retention versions for applications where low current and low stand-by voltages are required.

Writing data to the module is accomplished by bringing the chip enable ($\overline{CE}$) and write enable ($\overline{WE}$) inputs LOW. Data present on the eight I/O pins (I/O_1 - I/O_8) of the device is then written into the memory location specified by the address inputs (A_0 - A_{18}). Reading data from the device is accomplished by bringing chip enable ($\overline{CE}$) and ($\overline{OE}$) LOW while write enable remains inactive or HIGH. The data in the location specified by the address inputs will the appear on the I/O pins.

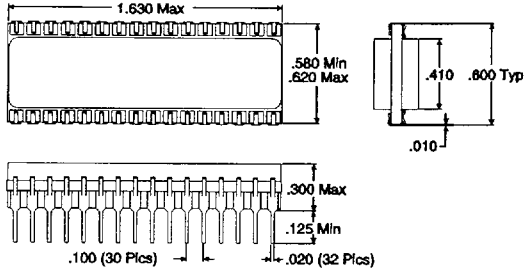
BLOCK DIAGRAM



PACKAGE OUTLINE



Package Type MO2, 32 Lead .600" Sidebrazed DIP



Package Type MO6, 32 Lead .600" Plastic DIP

ABSOLUTE MAXIMUM RATINGS

Storage Temperature	
Ceramic Packages	-65°C to +150°C
Plastic Packages	-55°C to +125°C
Voltage and Current	
Supply Voltage	-0.5 to +7.0V
Input Voltage	-0.5 to Vcc+0.5V
Input/Output Voltage	-0.5 to Vcc+0.5V
Allowable Power Dissipation	1W
Soldering Temperature*Time	260°C * 10s

OPERATING RANGES

Operating Temperature	
Commercial	0°C to +70°C
Industrial	-40°C to +85°C
Military	-55°C to +125°C
Voltage and Current	
Supply Voltage	4.5 to 5.5V
Input High Voltage	2.2 to Vcc+0.3V
Input Low Voltage	-0.3 to 0.8V

FUNCTIONAL TRUTH TABLE

$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	Mode	I/O1 - 8	Vcc Current
H	X	X	Not Selected	High Z	ISB1, ISB2
L	H	H	Output Disable	High Z	ICC
L	L	H	Read	Data Out	ICC
L	X	L	Write	Data In	ICC

CAPACITANCE (Ta=25°C, f=1MHz)

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input Capacitance	C_{IN}	VIN = 0V		15	25	pF
Input/Output Capacitance	$C_{I/O}$	VI/O = 0V		20	25	pF

Note: This parameter is sample tested and not 100% tested.

DC CHARACTERISTICS (Vcc=5V±10%, Ta=Topr)

Item	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input Leakage Current	IIL	VIN=GND or VCC	-10		10	μA
Output Leakage Current	IOL	VI/O=GND or VCC, $\overline{CE}$=VIH $\overline{OE}$=VIH or $\overline{WE}$=VIL	-10		10	μA
Average Operating Current	ICC	Min. Cycle, Iout=0mA		65	140	mA
Standby Current	ISB1	$\overline{CE}$≥VCC-0.2V, VIN≥VCC-0.2V		0.02	4	mA
	ISB2	$\overline{CE}$=VIH, VIN=VIL or VIH			40	mA
Output High Voltage	VOH	IOH=-4.0mA	2.4			V
Output Low Voltage	VOL	IOL=8.0mA			0.4	V

AC CHARACTERISTICS (Vcc=5V±10%, Ta=Topr)

AC Test Conditions

Item	Condition
Input Pulse High Level	VIH=3V
Input Pulse Low Level	VIL=0V
Input Pulse Rise Time	tr=5ns
Input Pulse Fall Time	tf=5ns
Input and Output Timing Level	1.5V
Output Load	Fig. 1

Output Load

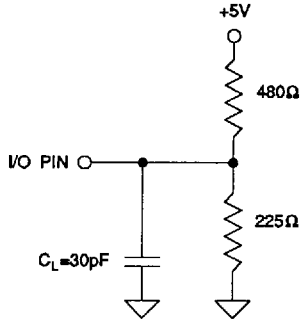


Fig. 1

Read Cycle

Item	Symbol	-35		-45		-55		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
Read Cycle Time	TAVAV	35		45		55		ns
Address Access Time	TAVQV		35		45		55	ns
Chip Enable Access Time	TELQV		35		45		55	ns
Output Enable to Output Valid	TGLQV		20		25		30	ns
Chip Enable to Output in High Z	TEHQZ		15		20		25	ns
Chip Enable to Output in Low Z	TELQX	15		15		15		ns
Output Disable to Output in High Z	TGHQZ		15		20		25	ns
Output Enable to Output in Low Z	TGLQX	5		5		5		ns
Output Hold from Address Change	TAVQX	5		5		5		ns

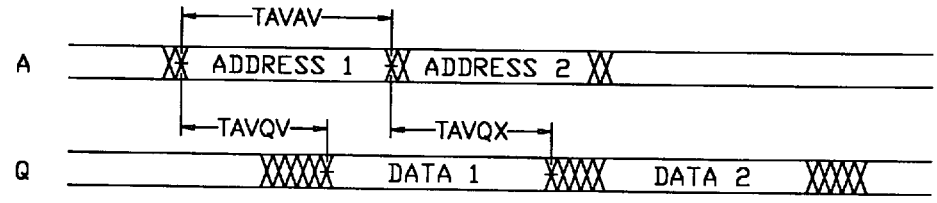
Write Cycle

Item	Symbol	-35		-45		-55		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
Write Cycle Time	TAVAV	35		45		55		ns
Address Valid to End of Write	TAVWH	30		40		50		ns
Chip Enable to End of Write	TELWH	30		40		50		ns
	TWLEH	30		40		50		ns
Data to Write Time Overlap	TDVWH	15		20		25		ns
	TDVEH	15		20		25		ns
Data Hold Time from Write	TWHDX	0		0		0		ns
	TEHDX	10		10		10		ns
Write Pulse Width	TWLWH	30		35		40		ns
	TELEH	30		35		40		ns
Address Set-up Time	TAVWL	10		10		10		ns
	TAVEL	0		0		0		ns
Write Recovery Time	TWHAX	5		5		5		ns
	TEHAX	5		5		5		ns
Write to Output in High Z	TWLQZ		20		20		20	ns
Output Active from End of Write	TWHQX	5		5		5		ns

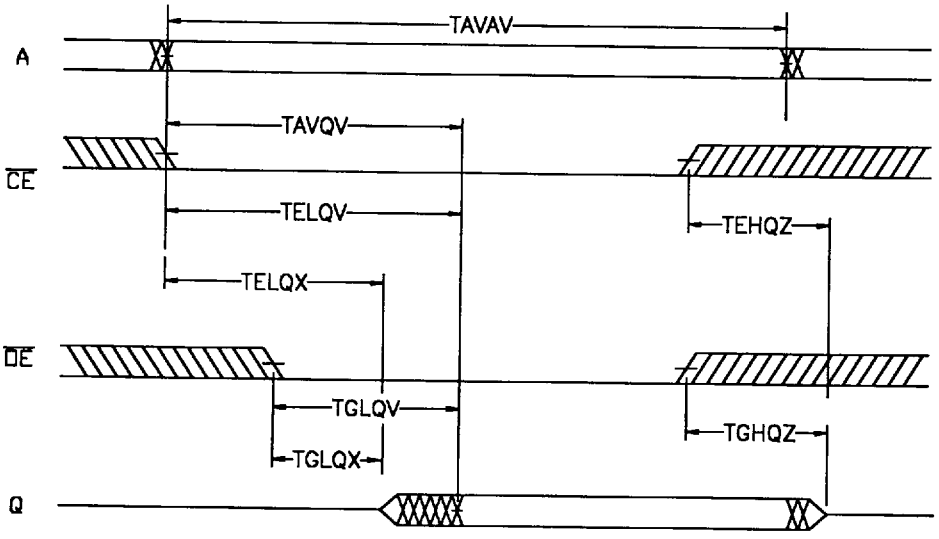
Timing Diagrams

Read Cycle Timing

Read Cycle 1: $\overline{CE}$=$\overline{OE}$=VIL, $\overline{WE}$=VIH

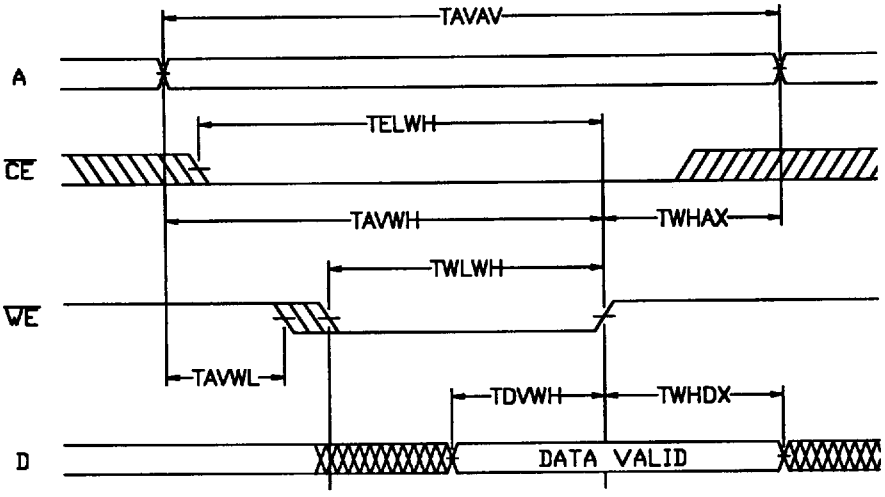


Read Cycle 2: $\overline{WE}$=VIH

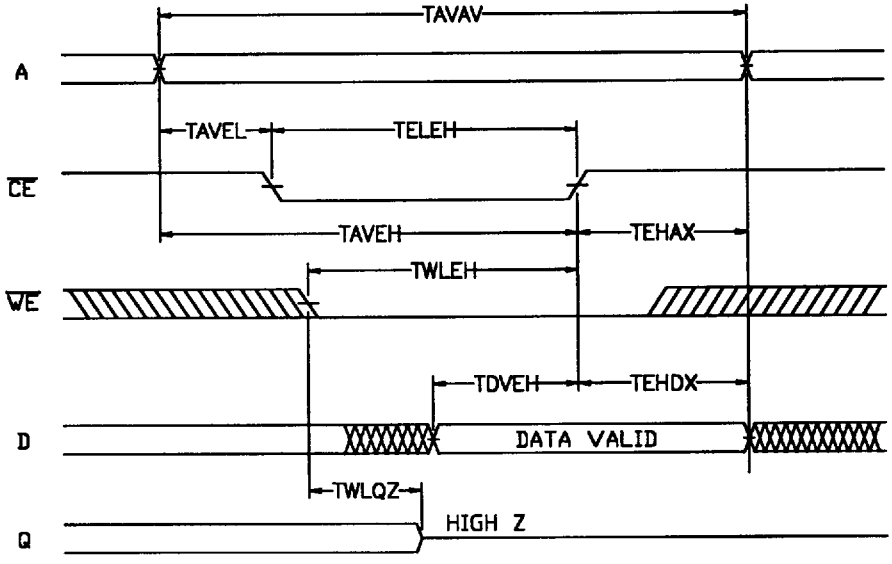


Write Cycle Timing

Write Cycle 1: $\overline{WE}$ Control



Write Cycle 2: $\overline{CE}$ Control



NOTES:

ORDERING INFORMATION

EMS256K8B *MO2* *-35* *C*

Temperature Range

C = Commercial (0 - 70°C)
I = Industrial (-40 - +85°C)
D = MIL Temp (-55 - +125°C)
M = MIL Screen (-55 - +125°C)

Speed

-35 = 35ns Access Time
-45 = 45ns Access Time
-55 = 55ns Access Time

Package

MO2 = .600" 32 Lead Ceramic DIP
MO6 = .600" 32 Lead Plastic DIP